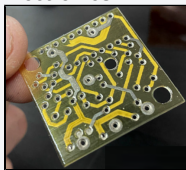
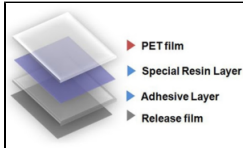


Multi-layer film forming

APPLICATIONS		KNOWLEDGE & MODELS		CAPABILITIES									
Electronics 	IC substrate manufacturing	Process	Vacuum Hot Press	Core Equipments at ADL Ewha Site									
Film formation		Material	Polyimide Film	Hot Press Machine									
			Cu Foil										
		Prepreg											
		Simulation (VE)	bending of FCCL										
Film formation 		Multi-layer film manufacturing											
Core Competitiveness at ADL Ewha		Evaluation Data Library		Project History									
Film Lamination Processing of Microelectronics		Customized Products	Liquid Crystal Polymer Products										
				<table><tr><th>No</th><th>Project Title</th></tr><tr><td>1</td><td>Flexible Copper Clad Laminate development</td></tr><tr><td>2</td><td></td></tr><tr><td>3</td><td></td></tr></table>		No	Project Title	1	Flexible Copper Clad Laminate development	2		3	
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